

Description

The **STB80NF10T4** uses advanced **APM-SGT™** technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 100V$ $I_D = 80A$

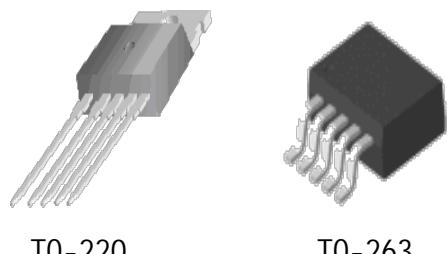
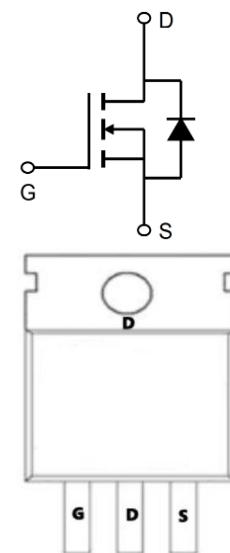
$R_{DS(ON)} < 12m\Omega$ @ $V_{GS}=10V$ (Type: **8.0mΩ**)

Application

Isolated DC

Motor control

Synchronous-rectification



T0-220

T0-263

Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DS}	Drain source voltage	100	V
V_{GS}	Gate source voltage	± 20	V
I_D	Continuous drain current, $T_C=25^\circ C$	80	A
I_{DM}	Pulsed drain current, $T_C=25^\circ C$	210	A
PD	Power dissipation, $T_C=25^\circ C$	107	W
EAS	Single pulsed avalanche energy ⁴⁾	183.8	mJ
T_{stg}, T_j	Operation and storage temperature	-55 to 150	°C
$R_{\theta JC}$	Thermal resistance, junction-case	1.17	°C/W
$R_{\theta JA}$	Thermal resistance, junction-ambient ⁴⁾	62	°C/W

Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
BVDSS	Drain-source breakdown voltage	$V_{GS}=0\text{ V}$, $I_D=250\text{ }\mu\text{A}$	100	111		V
VGS(th)	Gate threshold voltage	$V_{DS}=V_{GS}$, $I_D=250\text{ }\mu\text{A}$	2.0	3.0	4.0	V
RDS(ON)	Drain-source on-state resistance	$V_{GS}=10\text{ V}$, $I_D=20\text{ A}$		8	12.0	$\text{m}\Omega$
RDS(ON)	Drain-source on-state resistance	$V_{GS}=4.5\text{ V}$, $I_D=12\text{ A}$		12	14.0	$\text{m}\Omega$
IGSS	Gate-source leakage current	$V_{GS}=\pm 20\text{ V}$			± 100	nA
IDSS	Drain-source leakage current	$V_{DS}=100\text{ V}$, $V_{GS}=0\text{ V}$			1	uA
R_G	Gate resistance	$f=1\text{ MHz}$, Open drain		5.5		Ω
Ciss	Input capacitance	$V_{GS}=0\text{ V}$, $V_{DS}=50\text{ V}$, $f=100\text{ kHz}$		1998.1		pF
Coss	Output capacitance			321.7		pF
Crss	Reverse transfer capacitance			7.1		pF
td(on)	Turn-on delay time		$V_{GS}=10\text{ V}$,	22.1		ns
t_r	Rise time	$V_{DS}=50\text{ V}$,		5.2		ns
td(off)	Turn-off delay time	$R_G=2\text{ }\Omega$,		44		ns
t_f	Fall time	$I_D=25\text{ A}$, $V_{DS}=50\text{ V}$, $V_{GS}=10\text{ V}$		8.4		ns
Q_g	Total gate charge			28.9		nC
Q_{gs}	Gate-source charge			6		nC
Q_{gd}	Gate-drain charge			6.8		nC
Vplateau	Gate plateau voltage			3.7		V
I_s	Diode forward current			60		A
ISP	Pulsed source current	$I_s=20\text{ A}$, $V_{GS}=0\text{ V}$		180		
VSD	Diode forward voltage				1.3	V
trr	Reverse recovery time			102.9		ns
Q_{rr}	Reverse recovery charge	$I_s=25\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$		379		nC
Irrm	Peak reverse recovery current			6.4		A

Note :

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is $VDD=30\text{ V}$, $VGS=10\text{ V}$, $L=0.3\text{ mH}$, starting $T_j=25^\circ\text{C}$
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation

Typical Characteristics

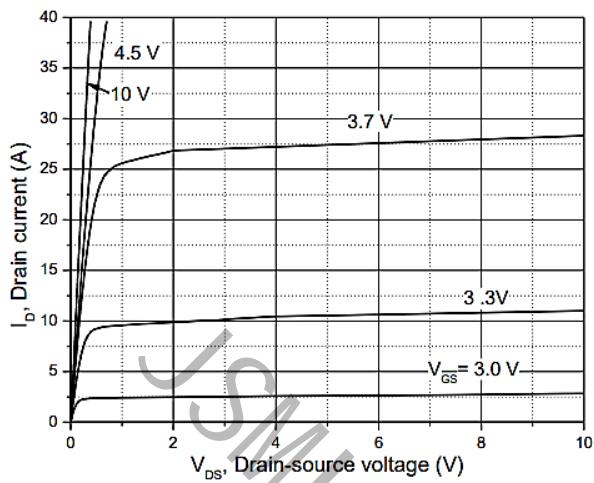


Figure 1. Typ. output characteristics

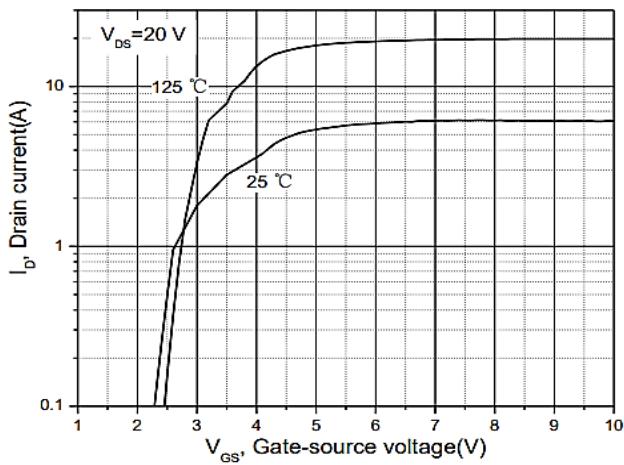


Figure 2. Typ. transfer characteristics

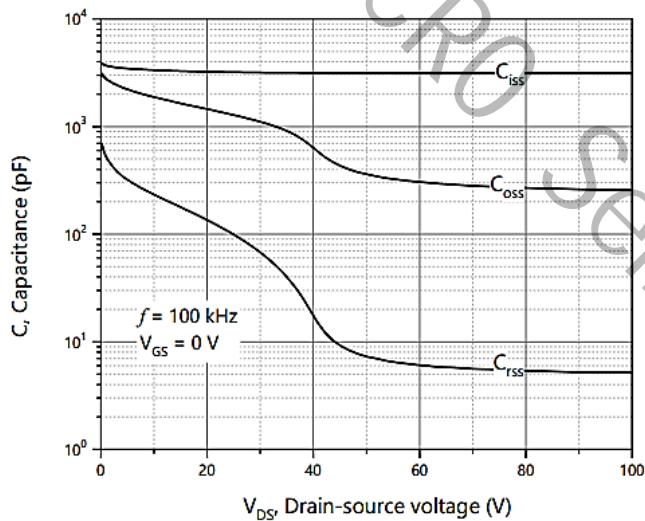


Figure 3. Typ. capacitances

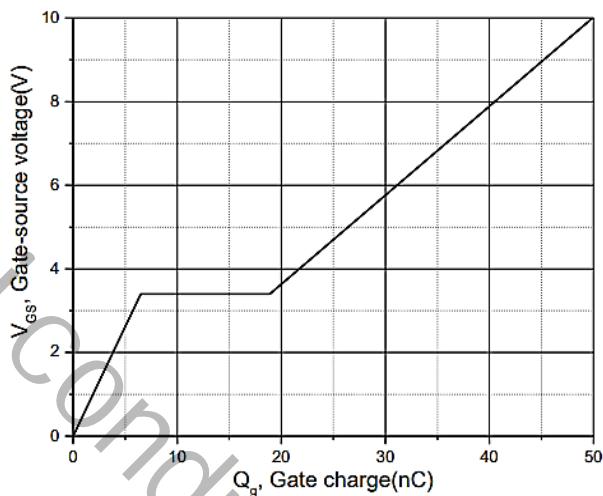


Figure 4. Typ. gate charge

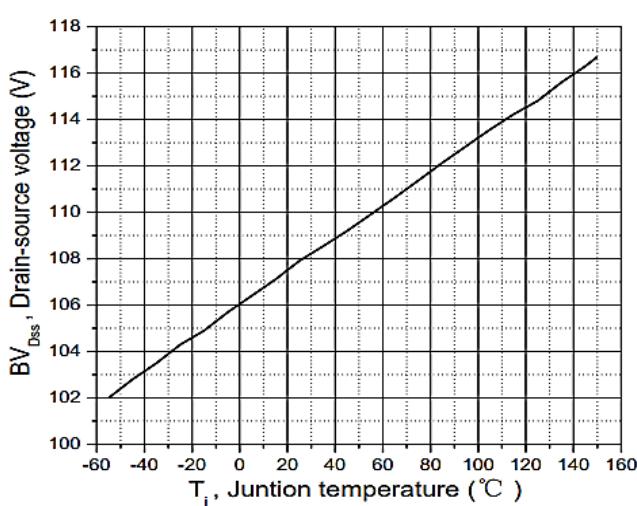


Figure 5. Drain-source breakdown voltage

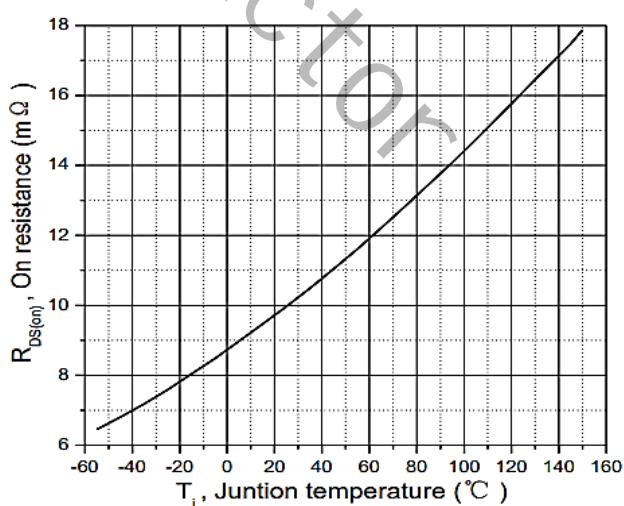


Figure 6. Drain-source on-state resistance

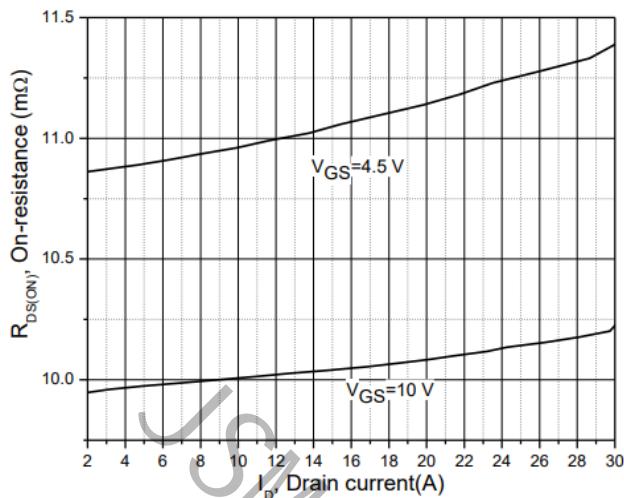


Figure 7. Drain-source on-state resistance

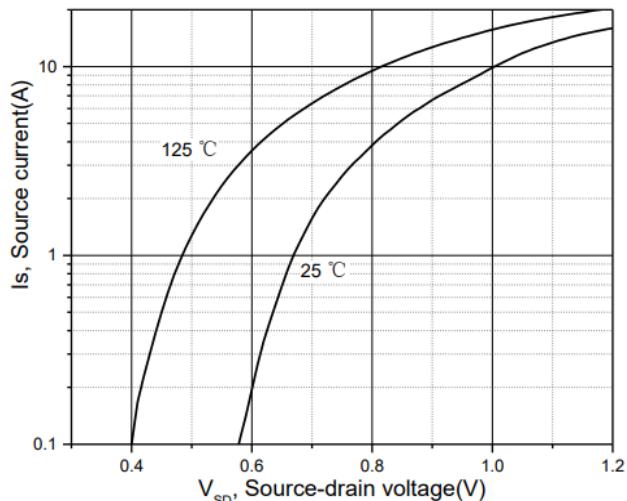


Figure 8. Forward characteristic of body diode

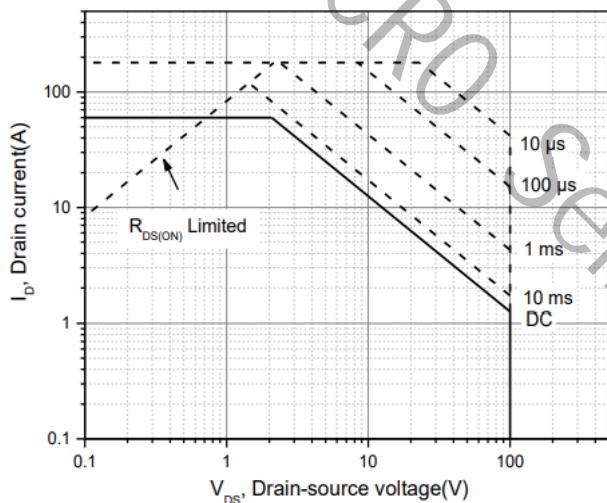
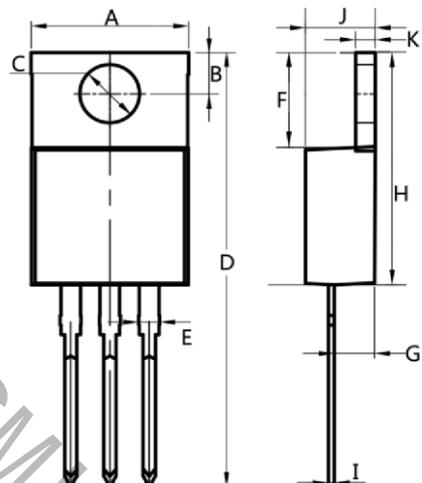


Figure 9. Safe operation area $T_c=25\text{ }^\circ\text{C}$

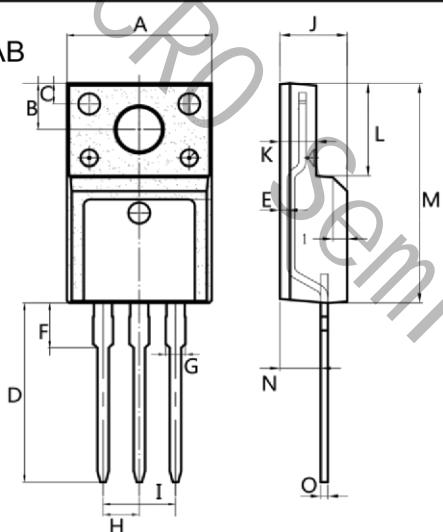
TO-220AB



Dim.	Min.	Max.
A	10.0	10.4
B	2.5	3.0
C	3.5	4.0
D	28.0	30.0
E	1.1	1.5
F	6.2	6.6
G	2.9	3.3
H	15.0	16.0
I	0.35	0.45
J	4.3	4.7
K	1.2	1.4

All Dimensions in millimeter

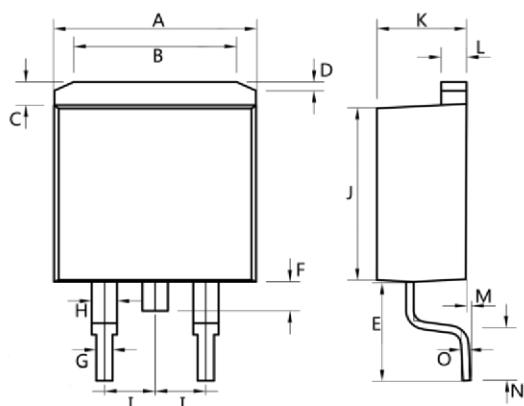
ITO-220AB



Dim.	Min.	Max.
A	9.9	10.3
B	2.9	3.5
C	1.15	1.45
D	12.75	13.25
E	0.55	0.75
F	3.1	3.5
G	1.25	1.45
H	Typ 2.54	
I	Typ 5.08	
J	4.55	4.75
K	2.4	2.7
L	6.35	6.75
M	15.0	16.0
N	2.75	3.15
O	0.45	0.60

All Dimensions in millimeter

TO-263



Dim.	Min.	Max.
A	10.0	10.5
B	7.25	7.75
C	1.3	1.5
D	0.55	0.75
E	5.0	6.0
F	1.4	1.6
G	0.75	0.95
H	1.15	1.35
I	Typ 2.54	
J	8.4	8.6
K	4.4	4.6
L	1.25	1.45
M	0.02	0.1
N	2.4	2.8
O	0.35	0.45

All Dimensions in millimeter